



Docket No. 57614 (71987)  
[formerly 71987-10000]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S. SERIAL NO.: 09/916,021

GROUP: 2815

FILED: July 26, 2001

EXAMINER: C. Chu

FOR: SEMICONDUCTOR PACKAGE WITH HEAT SINK

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, Washington, DC, 20231 on April 24, 2003.

By:

Steven M. Jensen

Commissioner for Patents  
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated December 31, 2002 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Please amend the application as follows:

IN THE CLAIMS

Please amend claims 1 and 12 as follows:

1. (Amended) A semiconductor package with a heat sink, comprising:  
a chip carrier;  
at least one chip mounted on the chip carrier and electrically connected to the chip carrier;

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